

IN THE
UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Tanya Jegeris Snyder, et al.

Serial No.: Not Yet Assigned

Examiner: Vu, Quang D.

Filing Date: 6/13/2003

Group Art Unit: 2811

Title: Wafer Bonding Using Reactive Foils For Massively Parallel Micro-Electromechanical System Packaging

COMMISSIONER FOR PATENTS
PO Box 1450
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

Sir:

Please amend the above-identified application as follows:

Page 1, line 1, insert the following new paragraph:

- () This is a Continuation of copending application Serial No. _____, filed on _____, the entire disclosure of which is incorporated herein by reference.
- (x) This is a Divisional of copending application Serial No. **10/461,291**, filed on **6/12/2003**, the entire disclosure of which is incorporated herein by reference.

In the Claims:

- (x) Cancel the following claims 1-19, 24-25 of the prior application. (At least one original claim must be retained for filing purposes).

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I hereby certify that this is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450.

By Ann Marie Radcliffe

Typed Name: Ann Marie Radcliffe

Respectfully submitted,
Tanya Jegeris Snyder, et al.

By Judy Yao Shie

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Date: 4/15/04

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